

L Number	Hits	Search Text	DB	Time stamp
2	2	("5323060").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 17:11
3	15	("3851221"   "4103318"   "4361261"   "4444349"   "4567643"   "4586642"   "4730232"   "4763188"   "4982265"   "5025306"   "5040052"   "5140404"   "5172215"   "5176311"   "5177032").PN.	USPAT	2002/11/07 17:11
4	74	5323060.URPN.	USPAT	2002/11/07 17:13
5	74	5323060.URPN.	USPAT	2002/11/07 17:15
1	135	257/685-686.ccls. and (conductive adj adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 18:03
6	2442	(257/\$.ccls. 438/\$.ccls.) and (conductive adj adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 17:28
7	691	(257/\$.ccls. 438/\$.ccls.) and (conductive adj adhesive) and (flip adj (chip die IC))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 17:46
8	4	((("5399898") or ("5323060")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 17:44
9	604	(257/\$.ccls. 438/\$.ccls.) and (conductive adj adhesive) and (flip adj (chip die IC)) and wir\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 17:54
10	115	(257/\$.ccls. 438/\$.ccls.) and (electrical\$4 adj conductive adj adhesive) and (flip adj (chip die IC)) and wir\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 17:56
11	20	257/685-686.ccls. and ((electrical\$4 adj conductive adj adhesive) ECA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 18:04
12	96	257/685-686,723-724,777-778.ccls. and ((electrical\$4 adj conductive adj adhesive) ECA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/07 18:20
13	17	438/107,109-110.ccls. and ((electrical\$4 adj conductive adj adhesive) ECA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 18:21